REVISIONS							
LTR	DESCRIPTION	DATE (YR-MO- DA)	APPROVED				
A	Convert to SMD format.Technical changes in table II. Editorial changes throughout. Redrawn.	92-11-18	M. L. Poelking				
В	Add device type 02. Add cage 34371 as source of supply. Technical changes in 1.3 and 1.4 and table I. Boilerplate update. Editorial changes throughout.	93-11-23	M. L. Poelking				

THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED

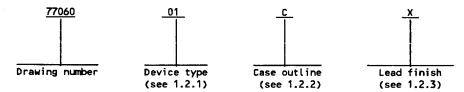
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OF SHEETS				SHEET	1_1_	2	3	4	5	6	7	8	9	10	11	12	13
PREPARED BY William E. Shoup DEFENS STANDARDIZED						DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444											
	ITARY	•		CHECKED BY A. J. Foley												DIIA	.
DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A			_	APPROVED BY N. A. Hauck					MICROCIRCUIT, DIGITAL CMOS, DUAL 4-INPUT OR GATES, MONOLITHIC SILICON								
				DRAWING APPROVAL DATE 77-12-29 REVISION LEVEL B						1			Γ				
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DESC FORM 193-1

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".
 - 1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Generic number</u>	<u>Circuit function</u>
4072B	Dual 4-input OR gate Dual 4-input OR gate

1.2.2 <u>Case outline(s)</u>. The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
С	GDIP1-T14 or CD1P2-T14	14	Dual-in-line
D	GDFP1-F14 or CDFP2-F14	14	Flat package

1.2.3 <u>Lead finish</u>. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein). Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

Supply voltage range (V _{DD}) (01)0.5 V dc to +18 V dc
Supply voltage range (V _{DD}) (02)
(voltages referenced to V_{cs} terminal)
Input voltage range
Storage temperature range
Maximum power dissipation, P _D (01) 200 mW <u>1</u> /
Maximum power dissipation, PD (02) 500 mW 1/
Lead temperature (soldering, 10 seconds) +260°C
Thermal resistance, junction-to-case (Θ_{JC}) See MIL-STD-1835
Junction temperature (T _j)

1.4 Recommended operating conditions.

Supply voltage range (VDD) (01)+3.0 V dc minimum to +15 V dc maximum
Supply voltage range (V_{DD}) (02)
Minimum high level input voltage (V_{IH})
Maximum low level input voltage (V_{11}) +1.5 V dc at $V_{DD} = 5$ V dc
Case operating temperature range55°C to +125°C

1/ For $T_A = +100$ °C, derate linearly at 12 mW/°C to 200 mW.

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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and bulletin</u>. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-1-38535

- Intergrated Circuits (Microcircuits) Manufacturing, General Specification For.

STANDARDS

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103

- List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-I-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-I-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-I-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein.
 - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.
 - 3.2.3 <u>Truth table</u>. The truth table shall be as specified on figure 2.
 - 3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.
- 3.2.5 Switching time waveforms. The switching time waveforms shall be as specified on figure 4.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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TABLE I. Electrical performance characteristics.

Test	Symbol		nditions T _C ≤ +125°C	Group A subgroups	Device type	L.	imits	Unit
		unless othe	rwise specified	Caba	Type	Min	Max	
High-level output voltage	v _{OH}	V _{DD} = 5.0 V V _{DD} = 10 V V _{DD} = 15 V	V _{IN} = 0 or V _{DD}	1,2,3	01	4.95 9.95 14.95		v
Low-level output voltage	v _{oL}	V _{DD} = 5.0 V V _{DD} = 10 V V _{DD} = 15 V	V _{IN} = V _{DD} or 0	1,2,3	01		0.05 0.05 0.05	V
Low-level input voltage	VIL	V ₀ = 4.5 V or 0.5 V	V _{DD} = 5.0 V	1,2,3	01		1.5	v
	1/	V ₀ = 9.0 V or 1.0 V	V _{DD} = 10 V	†			3.0	<u> </u>
		V _O = 13.5 V or 1.5 V	V _{DD} = 15 V	†			4.0	
High-level input voltage	V _{IH}	V ₀ = 4.5 V or 0.5 V	V _{DD} = 5.0 V	1,2,3	01	3.5		V
	1/	V _O = 9.0 V or 1.0 V	V _{DD} = 10 V	<u> </u>	 	7.0		
		V _O = 13.5 V or 1.5 V	V _{DD} = 15 V			11.0		
High-level output current	IOH	V ₀ = 4.6 V V ₀ = 9.5 V	V _{DD} = 5.0 V	1,2,3	01	-0.3		mA
		V ₀ = 13.5 V	v _{DD} = 15 v		- 	-2.2		
LOW-level output current	IOL	V _{OL} = 0.4 V		1,2,3	01	0.3		mA
		V _{OL} = 0.5 V		Ī	-	0.65		•
		v _{OL} = 1.5 v	V _{DD} = 15 V			2.2		
Input current	IIN	V _{DD} = 15 V		1,2,3	01		± 1.0	μA
nput capacitance	CIN	VIN = 0 V	See 4.3.1b	4	01		7.5	pF
Ruiescent current	I _{DO}	V _{DD} = 5.0 V V _{DD} = 10 V V _{DD} = 15 V		1,2,3	01		10.0 20.0 30.0	μΑ
unctional tests		See 4.3.1c		7,8	01			

See footnotes at end of table.

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TABLE 1. <u>Electrical performance characteristics</u> - Continued.

Test	Symbol	Conditions -55°C ≤ T _o ≤ +125°C	Group A subgroups	Device type	Limits		Unit
		-55°C ≤ T _C ≤ +125°C sul unless otherwise specified		'/-	Min	Max	
Propagation delay time	t _{PHL} ,	$C_L = 50 \text{ pF min} V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega \underline{2}/V_{DD} = 10 \text{ V}$ $\underline{3}/V_{DD} = 15 \text{ V}$	9	01		350 140 110	ns
		$C_L = 50 \text{ pF min}$ $V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega$ $V_{DD} = 10 \text{ V}$ $2/3$ $V_{DD} = 15 \text{ V}$	10,11			525 210 165	
Transition time	t _{THL} ,	$C_L = 50 \text{ pF min} V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega \frac{2}{2} / V_{DD} = 10 \text{ V}$ $\frac{3}{2} / V_{DD} = 15 \text{ V}$	9	01		200 100 80	ns
		$C_L = 50 \text{ pF min}$ $V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega$ $V_{DD} = 10 \text{ V}$ $2/3$ $V_{DD} = 15 \text{ V}$	10,11			300 150 120	

See footnotes at end of table.

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TABLE I. <u>Electrical performance characteristics</u>.

Test	Symbol		nditions _C ≤+125°C	Group A subgroups	Device type	Li	imits	Unit
		unless other	wise specified	subgroups	type	Min	Max	-
High-level output voltage	V _{OH}	$V_{DD} = 5.0 \text{ V } \underline{2}/$ $V_{DD} = 10 \text{ V } \underline{2}/$ $V_{DD} = 15 \text{ V}$	V _{IN} = 0 or V _{DD}	1,2,3	02	4.95 9.95 14.95		v
Low-level output voltage	v _{oL}	$V_{DD} = 5.0 \text{ V} \frac{2}{}$ $V_{DD} = 10 \text{ V} \frac{2}{}$ $V_{DD} = 15 \text{ V}$	V _{IN} = V _{DD} or 0	1,2,3	02		0.05 0.05	0.05 V
Low-level input voltage	VIL	V _O = 4.5 V or 0.5 V	V _{DD} = 5.0 V	1,2,3	02		1.5	V
	1/	V _O = 9.0 V or 1.0 V	V _{DO} = 10 V	 			3.0	
		V _O = 13.5 V or 1.5 V	V _{DD} = 15 V	†			4.0	
High-level input voltage	V _{IH}	V ₀ = 4.5 V or 0.5 V	V _{DD} = 5.0 V	1,2,3	02	3.5		V
	1/	V _O = 9.0 V or 1.0 V	V _{DD} = 10 V	†		7.0		†
		V _O = 13.5 V or 1.5 V	v _{DD} = 15 v			11.0	<u> </u> 	
High-level output current	IOH	L	v _{DD} = 5.0 v	1,2,3	02	-0.36		mA
		V ₀ = 9.5 V V ₀ = 13.5 V	V _{DD} = 10 V V _{DD} = 15 V	1		-0.9		+
Low-level output		V _{OL} = 0.4 V		1,2,3	02	0.36		mA
current	IOL	V _{OL} = 0.5 V	V _{DD} = 10 V	1		0.9		†
		V _{OL} = 1.5 V	V _{DD} = 15 V	†		2.4		†
Input current	IIN	V _{DD} = 20 V		1,2,3	02		± 1.0	μΑ
Input capacitance	CIN	V _{IN} = 0 V	See 4.3.1b	4	02		7.5	pF
Quiescent current	IDD	$V_{DD} = 5.0 \text{ V} \frac{2}{}$ $V_{DD} = 10 \text{ V} \frac{2}{}$ $V_{DD} = 15 \text{ V} \frac{2}{}$ $V_{DD} = 20 \text{ V} \frac{5}{}$		1,2,3	02		7.5 15.0 30.0 150	μΑ
functional tests		See 4.3.1c		7,8	02			

See footnotes at end of table.

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TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test Sy	Symbol	-55°C ≤ T _C ≤ +125°C	Group A subgroups	! :	Limits		Unit
	İ	unless otherwise specified		"	Min	Max	
Propagation delay time	t _{PHL} ,	$C_L = 50 \text{ pF min} V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega \underline{2}/V_{DD} = 10 \text{ V}$ $\underline{3}/V_{DD} = 15 \text{ V}$	9	02		250 120 90	ns
		$C_L = 50 \text{ pF min}$ $V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega$ $V_{DD} = 10 \text{ V}$ $2/3/2$ $V_{DD} = 15 \text{ V}$	10,11			375 180 135	
Transition time	t _{THL} ,	$C_L = 50 \text{ pF min} V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega \frac{2}{2}/V_{DD} = 10 \text{ V}$ $\frac{3}{2}$	9	02		200 100 80	ns
		$C_L = 50 \text{ pF min} V_{DD} = 5.0 \text{ V}$ $R_L = 200 \text{ k}\Omega V_{DD} = 10 \text{ V}$ $2/3/ V_{DD} = 15 \text{ V}$	10,11	† 		300 150 120	

 $[\]underline{1}\text{/ }V_{\text{IH}}$ and V_{IL} tests are not required if applied as forcing functions for the V_{OH} and V_{OL} tests.

5/ At -55°C test is performed with V_{DD} = 18 V.

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 $^{{\}it 2/}$ This condition is guaranteed, if not tested, to the specification limits in table I.

 $[\]underline{3}$ / See figure 4 for switching time waveforms.

 $[\]underline{4}$ / Subgroups 2 and 3 may be guaranteed, if not tested to the specification limits in table I.

Device type	All
Case outline	C and D
Terminal number	Terminal symbol
1	OUT 1Y IN 1A IN 1B IN 1C IN 1D NC VSS NC IN 2D IN 2C IN 2B IN 2A OUT 2Y
14	V _{DD}

FIGURE 1. Terminal connections.

	IN	OUTPUT		
A	В	С	D	γ
L	L	L	L	L
H	Ĺ	L	L	н
L	Н	L	L	н
H	Н	L	L	н
L	L	н	L	н
H	L	н	L	н
Ł	H	н	L	н
Н	H	н	L	н
L	L	L	н	н
Н	Ĺ	L	н	H
L	Н	L	н	н
Н	Н	L	н	Н
Ł	L	н	н	H
H	ļι	Н	Н	H
L	н	н	Н	H
H	Н	Н	Н	H

FIGURE 2. <u>Truth table</u>.

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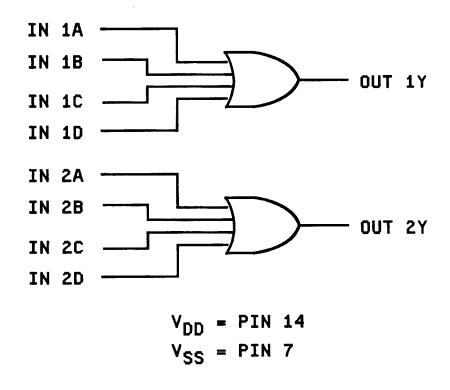
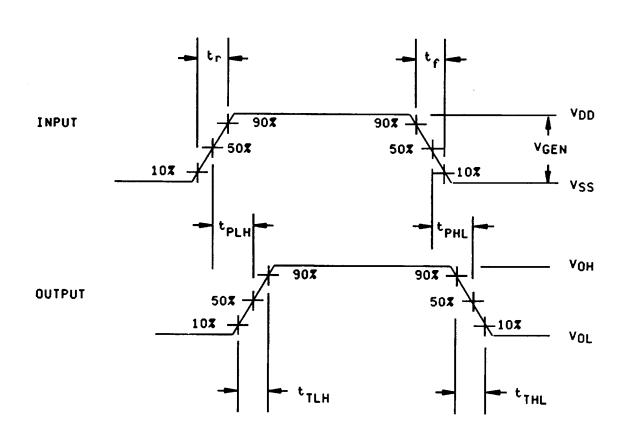


FIGURE 3. Logic diagram.

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DYNAMIC TEST WAVEFORMS-01

DYNAMIC TEST WAVEFORMS-02

Input pulse

V_{GEN} = V_{DD} ±1.0%

t_{PH} = 1.0 ±0.1 µs

t_r = t_f = 20 ±2 ns

PRR = 200 kHz

Input pulse V_{GEN} = V_{DD} t_r = t_f = 20 ns PRR = 200 kHZ

FIGURE 4. Switching time waveforms.

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- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change</u>. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 <u>Verification and review</u>. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	,
Final electrical test parameters (method 5004)	1*, 2, 3, 7,
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroup 4 (C_{IN} measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance. Capacitance shall be measured between the designated terminal and V_{SS} at a frequency of 1 MHz. Test all applicable pins on 5 devices with zero failures.
 - c. Subgroups 7 and 8 tests shall verify the truth table as shown on figure 2.
 - 4.3.2 Groups C and D inspections.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125$ °C, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
 - 5. PACKAGING
- 5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein).

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^{**} Subgroups 10 and 11, if not tested, shall be guaranteed to the limits specified in table I.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistic purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444, or telephone (513) 296-8525.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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